

[Document Name] Abstract

An object of the present invention is to provide a multilayered printed wiring board provided with split
5 through holes excellent in through-hole formability and co-planarity in inner layer wirings around through holes for providing of a conduction isolation portion. To achieve the object, "a copper clad laminate provided with a protective layer for manufacturing of a printed wiring
10 board having a conduction isolation portion electrically isolating a through hole, the copper clad laminate is characterized in that the copper clad laminate is provided with a protective layer on the surface that can be released after forming of the through holes for
15 providing of a conduction isolation portion and filling of the through holes for providing of a conduction isolation portion by a plating resist" is employed.